

CEM4311-VB Datasheet P-Channel 30-V (D-S) MOSFET

PRODUCT SUMMARY					
V _{DS} (V)	$R_{DS(on)}$ (Ω)	I _D (A) ^d	Q _g (Typ.)		
- 30	0.018 at V _{GS} = - 10 V	- 9.0	13 nC		
- 30	0.024 at V _{GS} = - 4.5 V	- 7.8	13110		

FEATURES

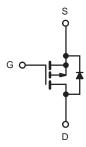
- Halogen-free According to IEC 61249-2-21 Definition
- Trench Power MOSFET
- 100 % R_g Tested

Pb-free RoHS COMPLIANT HALOGEN

FREE

APPLICATIONS

- Load Switch
- · Battery Switch



P-Channel MOSFET

	SO-8	
S 1		8 D
S 2		7 D
S 3		6 D
G 4		5 D
	Top View	

Parameter	Symbol	Limit	Unit		
Drain-Source Voltage	V _{DS}	- 30	V		
Gate-Source Voltage		V_{GS}	± 20	¬	
	T _C = 25 °C		- 9.0		
Continuous Drain Current (T _{.1} = 150 °C)	T _C = 70 °C		- 7.2	A	
Continuous Diain Current (1) = 150 °C)	T _A = 25 °C	l _D	- 7.0 ^{a, b}		
	T _A = 70 °C		- 5.6 ^{a, b}		
Pulsed Drain Current	I _{DM}	- 30			
Continuous Course Danie Biodo Current	T _C = 25 °C	1	- 3.5		
Continuous Source-Drain Diode Current	T _A = 25 °C	- I _S -	- 2.1 ^{a, b}	1	
	T _C = 25 °C		4.2		
Mariana Paran Piada di a	T _C = 70 °C		2.7	,,,	
Maximum Power Dissipation	T _A = 25 °C	P _D	2.5 ^{a, b}	W	
	T _A = 70 °C	1	1.6 ^{a, b}		
Operating Junction and Storage Temperature Rang	T _J , T _{stq}	- 55 to 150	°C		

THERMAL RESISTANCE RATINGS						
Parameter		Symbol	Typical	Maximum	Unit	
Maximum Junction-to-Ambient ^{a, c}	t ≤ 10 s	R _{thJA}	40	50	°C/W	
Maximum Junction-to-Foot	Steady State	R _{thJF}	24	30	C/VV	

Notes:

- a. Surface mounted on 1" x 1" FR4 board.
- b. t = 10 s.
- c. Maximum under Steady State conditions is 95 °C/W.
- d. Based on $T_C = 25$ °C.



Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit	
Static							
Drain-Source Breakdown Voltage	V _{DS}	$V_{GS} = 0 \text{ V}, I_D = -250 \mu\text{A}$	- 30			V	
V _{DS} Temperature Coefficient	$\Delta V_{DS}/T_{J}$	L = 250 uA		- 31		m\//0C	
V _{GS(th)} Temperature Coefficient	$\Delta V_{GS(th)}/T_J$	- I _D = - 250 μA		4.5		mV/°C	
Gate-Source Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}, I_{D} = -250 \mu A$	- 1.0		- 2.5	V	
Gate-Source Leakage	I _{GSS}	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$			± 100	nA	
Zara Cata Valtaga Drain Current	I	V _{DS} = - 30 V, V _{GS} = 0 V			-1		
Zero Gate Voltage Drain Current	IDSS	V _{DS} = - 30 V, V _{GS} = 0 V, T _J = 55 °C			- 5	μA	
On-State Drain Current ^a	I _{D(on)}	$V_{DS} \le -5 \text{ V}, V_{GS} = -10 \text{ V}$	- 20			Α	
5 1 6 9 9 1 5 1 1 3	D	V _{GS} = - 10 V, I _D = - 7.0 A		0.018		Ω	
Drain-Source On-State Resistance ^a	R _{DS(on)}	V _{GS} = - 4.5 V, I _D = - 5.6 A		0.024			
Forward Transconductance ^a	9 _{fs}	V _{DS} = - 15 V, I _D = - 7.0 A		18		S	
Dynamic ^b					_		
Input Capacitance	C _{iss}			1455		pF	
Output Capacitance	C _{oss}	V _{DS} = - 15 V, V _{GS} = 0 V, f = 1 MHz		180			
Reverse Transfer Capacitance	C _{rss}			145			
<u>'</u>	Q _g	V _{DS} = - 15 V, V _{GS} = - 10 V, I _D = - 7.0 A	25 3		38		
Total Gate Charge				13	20		
Gate-Source Charge	Q _{qs}	$V_{DS} = -15 \text{ V}, V_{GS} = -4.5 \text{ V}, I_{D} = -7.0 \text{ A}$		3.5		nC	
Gate-Drain Charge	Q _{qd}			5.5		1	
Gate Resistance	R _q	f = 1 MHz	0.4	2.0	4.0	Ω	
Turn-On Delay Time	t _{d(on)}			10	20		
Rise Time	t _r	$V_{DD} = -15 \text{ V}, R_{L} = 2.7 \Omega$		13	20	1	
Turn-Off DelayTime	t _{d(off)}	$I_{D} \cong -5.6 \text{ A}, V_{GEN} = -10 \text{ V}, R_{g} = 1 \Omega$		23	35		
Fall Time	t _f	, and the second		9	18	1	
Turn-On Delay Time	t _{d(on)}			38	57	ns	
Rise Time	t _r	$V_{DD} = -15 \text{ V}, R_{L} = 2.7 \Omega$		89	134		
Turn-Off DelayTime	t _{d(off)}	$I_D \cong -5.6 \text{ A}, V_{GEN} = -4.5 \text{ V}, R_g = 1 \Omega$		22	33		
Fall Time	t _f			11	17		
Drain-Source Body Diode Characteris	stics						
Continous Source-Drain Diode Current	I _S	T _C = 25 °C			- 6.5	_	
Pulse Diode Forward Current	I _{SM}	-			- 30	A	
Body Diode Voltage	V _{SD}	I _S = - 5.6 A, V _{GS} = 0 V		- 0.71	- 1.2	V	
Body Diode Reverse Recovery Time	t _{rr}	- 55		22	33	ns	
Body Diode Reverse Recovery Charge	Q _{rr}	I _F = -5.6 A, dl/dt = 100 A/μs, T _J = 25 °C		17	26	nC	
Reverse Recovery Fall Time	t _a			13			
Reverse Recovery Rise Time	t _b			9		ns	

Notes:

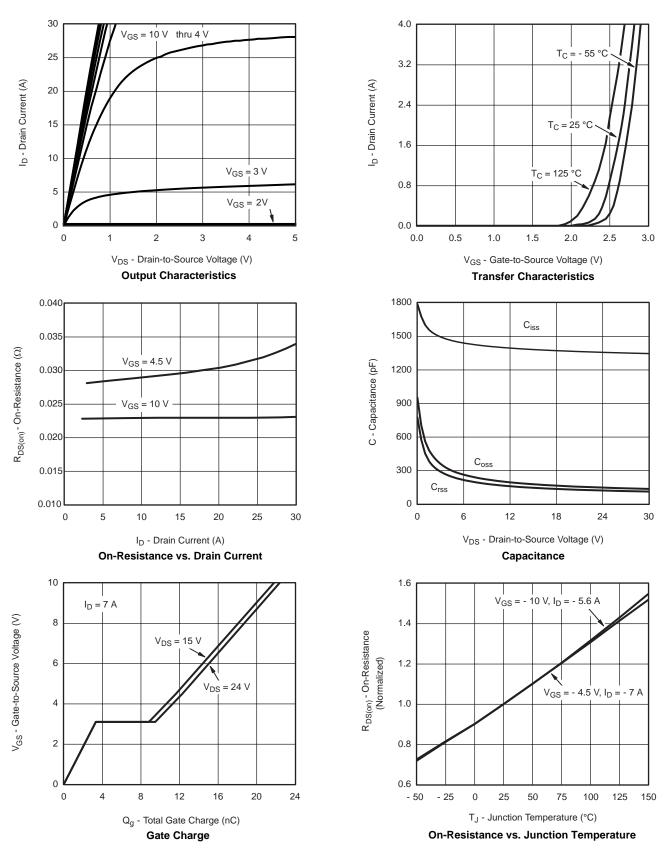
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

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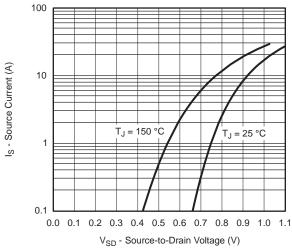
a. Pulse test; pulse width $\leq 300~\mu s,$ duty cycle $\leq 2~\%.$

b. Guaranteed by design, not subject to production testing.

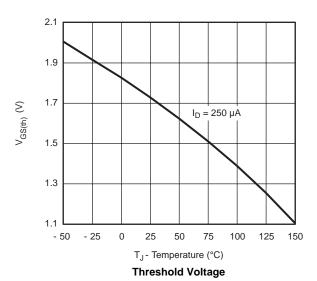






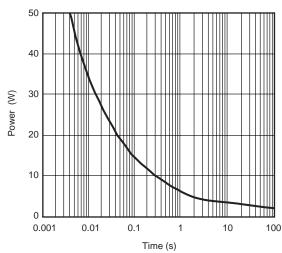


Source-Drain Diode Forward Voltage

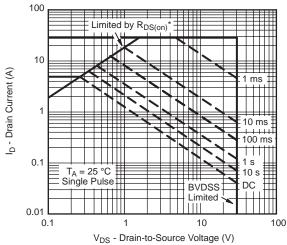


V_{GS} - Gate-to-Source Voltage (V)

On-Resistance vs. Gate-to-Source Voltage



Single Pulse Power, Junction-to-Ambient

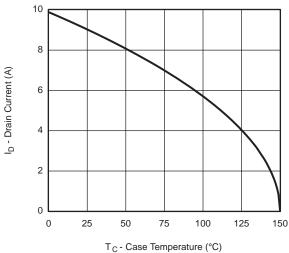


 * VGS > minimum VGS at which RDS(on) is specified

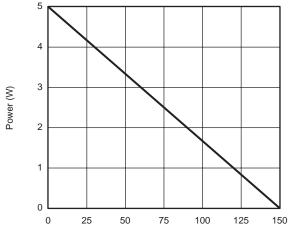
Safe Operating Area

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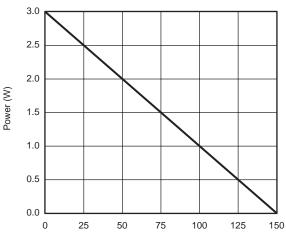








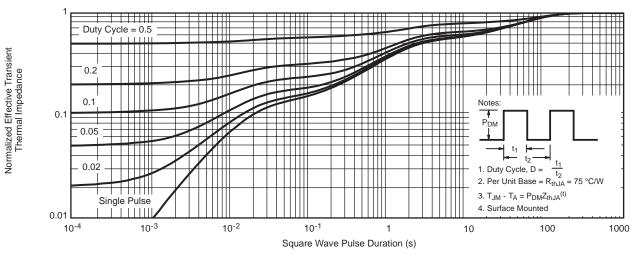
T_C - Case Temperature (°C) Power, Junction-to-Foot



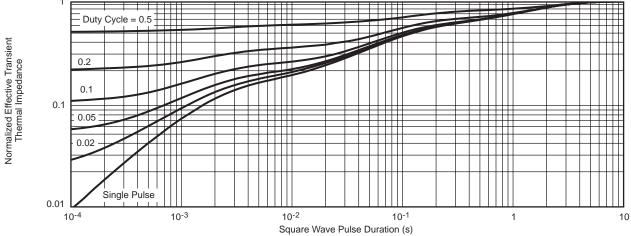
T_A - Ambient Temperature (°C) Power Derating, Junction-to-Ambient

^{*} The power dissipation P_D is based on $T_{J(max)}$ = 150 °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package





Normalized Thermal Transient Impedance, Junction-to-Ambient

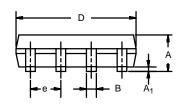


Normalized Thermal Transient Impedance, Junction-to-Foot



SOIC (NARROW): 8-LEADJEDEC Part Number: MS-012







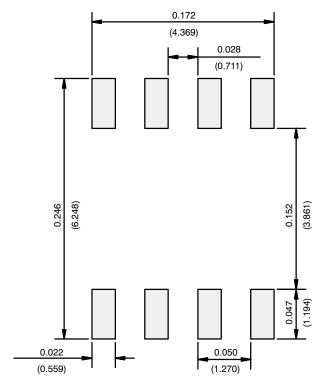
	MILLIMETERS		INC	HES	
DIM	Min	Max	Min	Max	
Α	1.35	1.75	0.053	0.069	
A ₁	0.10	0.20	0.004	0.008	
В	0.35	0.51	0.014	0.020	
С	0.19	0.25	0.0075	0.010	
D	4.80	5.00	0.189	0.196	
E	3.80	4.00	0.150	0.157	
е	1.27 BSC		0.050 BSC		
Н	5.80	6.20	0.228	0.244	
h	0.25	0.50	0.010	0.020	
L	0.50	0.93	0.020	0.037	
q	0°	8°	0°	8°	
S	0.44	0.64	0.018	0.026	
ECN: C-06527-Pay I 11-San-06					

ECN: C-06527-Rev. I, 11-Sep-06

DWG: 5498



RECOMMENDED MINIMUM PADS FOR SO-8



Recommended Minimum Pads Dimensions in Inches/(mm)



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